

### 描述 / Descriptions

SOT-89 塑封封装 PNP 半导体三极管。Silicon PNP transistor in a SOT-89 Plastic Package.

### 特征 / Features

饱和压降低,与 2SD1766 互补。

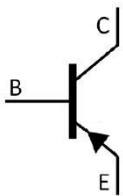
Low  $V_{CE(sat)}$ , complements the 2SD1766.

### 用途 / Applications

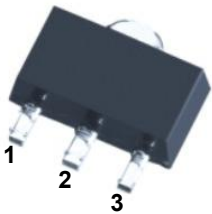
用于中功率放大。

Medium power amplifier applications.

### 内部等效电路 / Equivalent Circuit



### 引脚排列 / Pinning



PIN1 : Base      PIN 2 : Collector      PIN 3 : Emitter

### 印章代码 / Marking

$h_{FE}$ Classifications Symbol	P	Q	R
$h_{FE}$ Range	82~180	120~270	180~390
Marking	HBCP*	HBCQ*	HBCR*

**极限参数 / Absolute Maximum Ratings(Ta=25°C)**

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Collector to Base Voltage	$V_{CBO}$	-40	V
Collector to Emitter Voltage	$V_{CEO}$	-32	V
Emitter to Base Voltage	$V_{EBO}$	-5.0	V
Collector Current-Continuous	$I_C$	-2.0	A
Collector Current-Continuous(Pulse)	$I_{CP}$	-3.0	A
Collector Power Dissipation	$P_C$	0.5	W
	* $P_C$	2.0	W
Junction Temperature	$T_j$	150	°C
Storage Temperature Range	$T_{stg}$	-55~150	°C

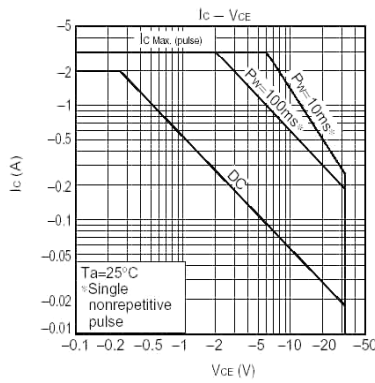
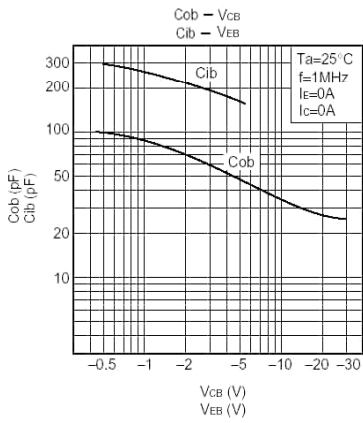
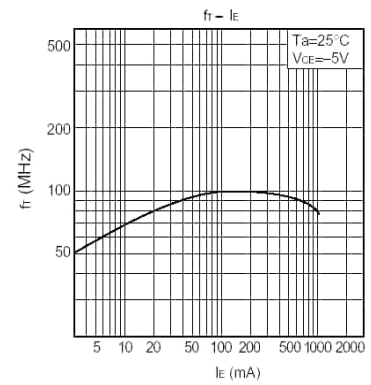
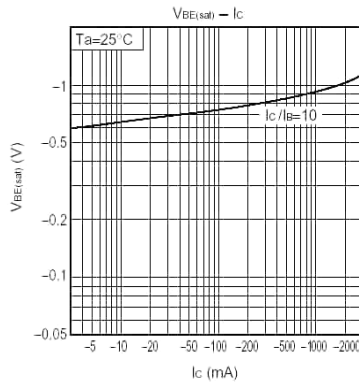
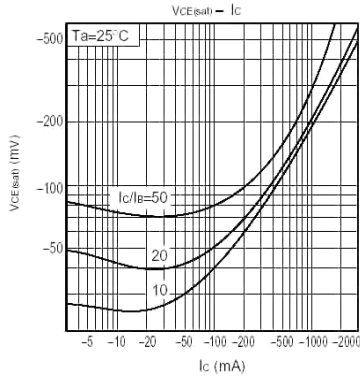
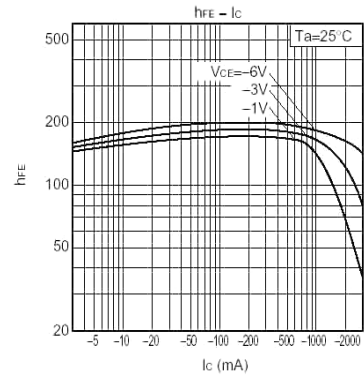
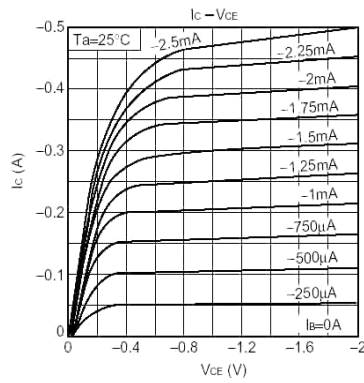
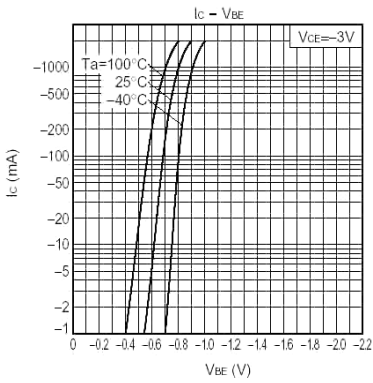
\*:mounted on 40×40×0.7mm ceramic board.

\*:装于 40×40×0.7m 的陶瓷板上。

**电性能参数 / Electrical Characteristics(Ta=25°C)**

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Collector to Base Breakdown Voltage	$V_{CBO}$	$I_C=-50\mu A$ $I_E=0$	-40			V
Collector to Emitter Breakdown Voltage	$V_{CEO}$	$I_C=-1.0mA$ $I_B=0$	-32			V
Emitter to Base Breakdown Voltage	$V_{EBO}$	$I_E=-50\mu A$ $I_C=0$	-5.0			V
Collector Cut-Off Current	$I_{CBO}$	$V_{CB}=-20V$ $I_E=0$			-1.0	$\mu A$
Emitter Base Cut-Off Current	$I_{EBO}$	$V_{EB}=-4.0V$ $I_C=0$			-1.0	$\mu A$
DC Current Gain	$h_{FE}$	$V_{CE}=-3.0V$ $I_C=-0.5A$	82		390	
Collector to Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C=-2.0A$ $I_B=-0.2A$		-0.5	-0.8	V
Transition Frequency	$f_T$	$V_{CE}=-5.0V$ $I_C=-0.5A$ $f=30MHz$		100		MHz
Collector Output Capacitance	$C_{ob}$	$V_{CB}=-10V$ $I_E=0$ $f=1.0MHz$		50		pF

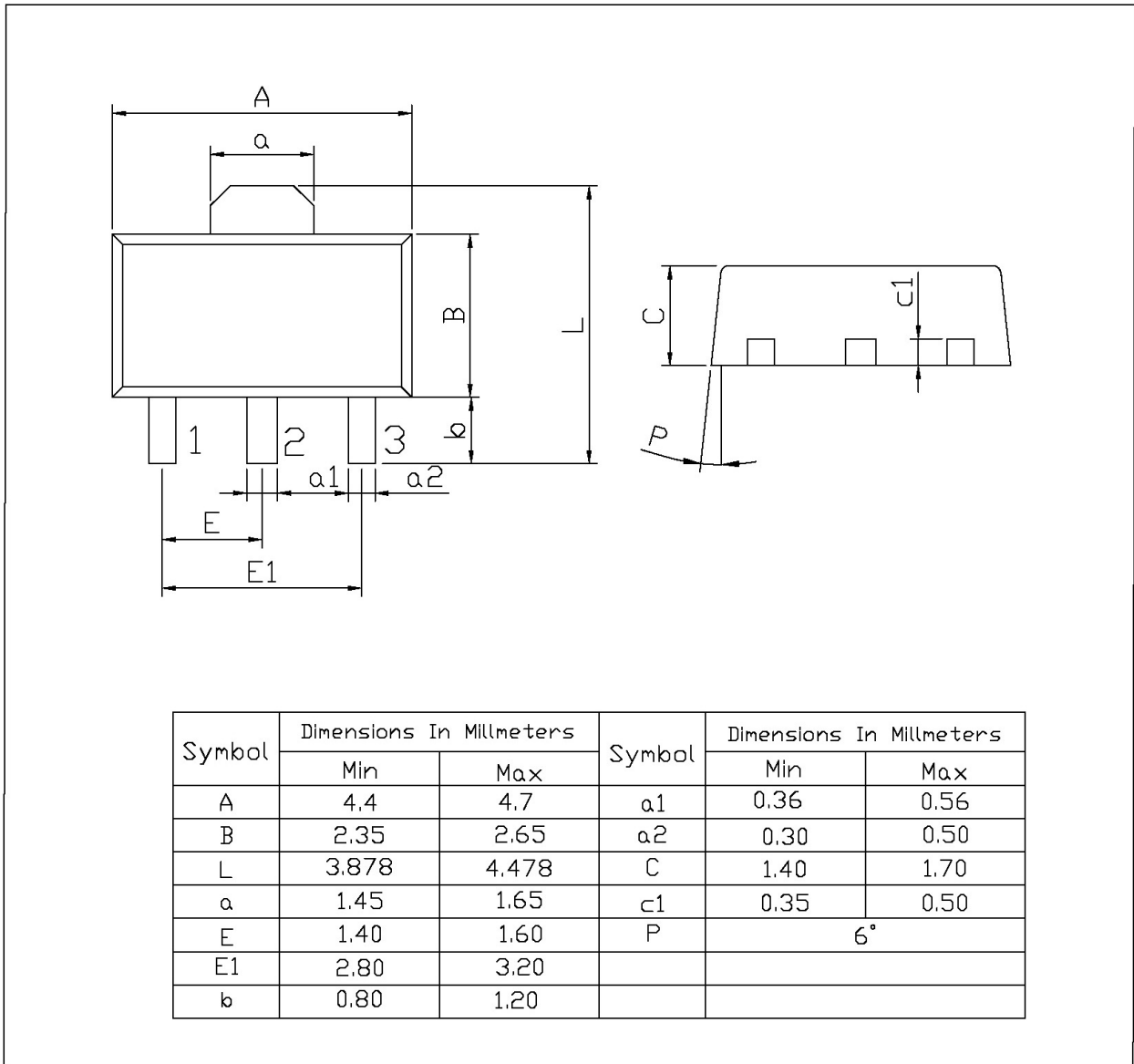
**电参数曲线图 / Electrical Characteristic Curve**



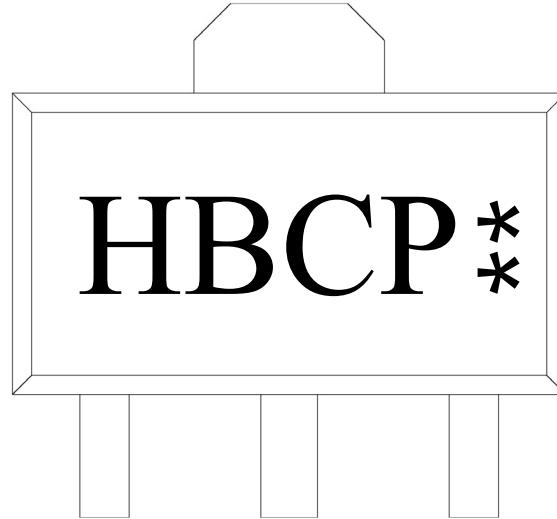
外形尺寸图 / Package Dimensions

SOT-89

单位: mm



印章说明 / Marking Instructions



说明：

H： 为公司代码

BC： 为型号代码

P： 为 h<sub>FE</sub> 分档代码

\*\*： 为生产批号代码，随生产批号变化。

Note:

H: Company Code.

BC: Product Type.

P: h<sub>FE</sub> Classifications Symbol

\*\* : Lot No. Code, code change with Lot No.

**回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)**



说明：

- 1、预热温度 25~150°C，时间 60~90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2~10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

**耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions**

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

**包装规格 / Packaging SPEC.**

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-89	1,000	7	7,000	8	56,000	7" ×12	180×120×180	385×257×392

**使用说明 / Notices**